

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Filed: July 3, 2003	)	1450, Alexandria, VA 22313-1450 on
	)	this date:
For: Method of Manufacturing a	)	
Semiconductor Wafer	)	December 27, 2004
	)	
Group Art Unit: 2813	)	ander In Jamenee
Examiner: Chandra P. Chaudhari	)	Andrew M. Lawrence, Reg. No. 46,130 Attorney for Applicants

## **AMENDMENT "A"**

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

This paper is in response to the official action dated August 25, 2004 (hereafter, "the official action").

The Amendments to the Specification section begins on page 2 of this paper.

The Complete Listing of Claims begins on page 3 of this paper.

The **Remarks** section begins on page 4 of this paper.